CLAIMS

1. A leadframe comprising an element mount frame, a fitting frame that is laid beside the element mount frame with a gap left in between, and a shielding frame that is tied via a tying portion to the fitting frame and that can be brought into such a state as to cover the element mount frame.

2. The leadframe of claim 1,

wherein the tying portion is provided at both ends of the gap.

3. The leadframe of claim 1,

wherein the element mount frame and the fitting frame are separate.

4. The leadframe of one of claims 1 to 3,

wherein the fitting frame is, in a portion thereof near the tying portion, shaped symmetrically about the tying portion.

5. A photodetector module comprising a photodetector element, an element mount frame on which the photodetector element is mounted, a fitting frame that is laid beside the element mount frame with a gap left in between, a shielding frame that is tied via a tying portion to the fitting frame and that can be brought into such a state as to cover the element mount frame, and molding resin in which the element mount frame and the fitting frame are sealed.

6. The photodetector module of claim 5,

wherein the element mount frame and the shielding frame are kept at an equal potential.

7. The photodetector module of claim 5,

wherein the element mount frame and the shielding frame are kept at different potentials.

8. The photodetector module of claim 5,

wherein a circuit element that processes a signal from the photodetector element is mounted on the element mount frame.

9. The photodetector module of claim 5,

wherein the element mount frame and the gap have nearly equal lengths.